

30th European Symposium on Reliability of Electron Devices, Failure Physics and Analysis

September 23-26, 2019

Centre de congrès P. Baudis,
Toulouse (France)

ESREF
2019

1st CALL FOR PAPERS

ESREF 2019, the 30th European Symposium on Reliability of Electron Devices, Failure Physics and Analysis, will take place in Toulouse (France) from 23rd to 26th September 2019 at *Centre de Congrès Pierre Baudis*.

This international symposium continues to focus on recent developments and future directions in Quality and Reliability Management of materials, devices and circuits for micro-, nano-, and optoelectronics. It provides a European forum for developing all aspects of reliability management and innovative analysis techniques for present and future electronic applications.

A word from the conference chairs

ESREF 2019 will be held in Toulouse - world center for aeronautics with Airbus assembly line, European capital of the space industry and leader in France for embedded electronic systems. Toulouse, called "Ville rose" (Pink city) for its characteristic architecture based on terra cotta bricks, combines a strong living spirit with a brilliant past. It is the third French university with more than 100,000 students and 147 laboratories. It is definitely turned towards the future with a large number of cutting-edge businesses in aeronautics, information technologies and spatial industries, as well as many research institutes. Hosting ESREF 2019 in this rich environment is a great opportunity since reliability in these particular applications is a very hot topic with strong challenges such as zero ppm failure and harsh environments. For this 30th edition, in addition to the core topics of the conference, we would like to involve the major actors of aeronautics, space and embedded systems industry to provide specific topics such as radiation hardening, very long-term reliability, high/low temperature challenges, obsolescence and counterfeit issues, wide bandgap power devices for the more electric aircraft and other embedded system applications. A special session for Nanosatellite reliability is proposed. In the continuity of previous conferences, ESREF 2019 is also hosting several workshops and welcomes new ones related to these specific topics.

We are looking forward to welcoming you for a memorable experience!

Nicolas NOLHIER
ESREF 2019 Chair

Guillaume BASCOUL
ESREF 2019 Vice-Chair

Technical Program Chair : Fabrice CAIGNET, H  l  ne FREMONT, Nathalie LABAT, Fran  ois MARC

SCOPE OF PAPERS

Papers are requested on the following topics:

Quality and Reliability assessment techniques and methods for Devices and Systems

Physical Modeling and Simulation for Reliability Prediction

Advanced Failure Analysis: Defect Detection and Analysis

Failure Mechanisms in New Materials and Transistors

Failure analysis and Reliability of Advanced and Nanoscale electronics

Focused Ion Beam (EFUG)

Power Devices Reliability and Failure Analysis

Packaging and Assembly Reliability and Failure Analysis

Space, Aeronautic and embedded systems

Special session : Nanosatellite Reliability

Tutorials by experts will provide review presentation of relevant topics and **Invited papers** will introduce the mainstream topics.

Workshops organized in correlation with the ESREF conference will give the opportunity to exchange the know-how and field returns on specific topics. For further information concerning the Scientific Program, please contact: esref2019-event@sciencesconf.org

Exhibition - The Symposium will feature the latest in service providers, equipment manufacturers and suppliers in these fields.

You can enjoy early signups (Fall 2018) and early bird (up to June 2019) discounts. For further information concerning the equipment exhibition, please contact: esref2019-expo@sciencesconf.org

Sponsor the event and get advantages of sponsor packages (platinum, gold and silver). Combine sponsorship with early sign up at exhibition and get impressive discounts and advantages. For further information concerning the sponsoring, please contact: esref2019-sponsor@sciencesconf.org

DEADLINES

11 March 2019 Submission of four-page extended summary to be uploaded at: <http://esref2019.sciencesconf.org>

29 April 2019 Notification of acceptance

20 May 2019 Submission of extended paper

Elsevier Ltd will publish the ESREF 2019 proceedings as a special issue of the Microelectronics Reliability journal.

10 June 2019 Upload of final paper to the online Elsevier Editorial System (EES)



organized by:

Conference Website : <http://esref2019.sciencesconf.org> / Contact : esref2019@sciencesconf.org